AMENDMENT TRANSMITTAL LETTER

	Docket No. TESSERA 3.0-109 CIP DIV

Application No. 09/776,356	Filing Date February 2, 2001	Examiner D. Graybill	Art Unit 2827

Applicant(s): Young-Gon Kim, Belgacem Haba, and Vernon Solberg

Invention: STACKED MICROELECTRONIC ASSEMBLY AND METHOD THEREFOR

TO THE COMMISSIONER FOR PATENTS

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED					
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
Total Claims	33	- 20 =	13	x 18.00	234.00
Independent Claims	4	- 4 =		x	0.00
Multiple Dependent Claims (check if applicable) ☐					
Other fee (please specify):					
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:					234.00

[x] Large Entity   ☐ Small Entity

☐ No additional fee is required for this amendment.

[x] Please charge Deposit Account No. ___12-1095___ in the amount of $ ___234.00___ .
A duplicate copy of this sheet is enclosed.

☐ A check in the amount of $ _____ to cover the filing fee is enclosed.

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[x] The Commissioner is hereby authorized to charge and credit Deposit Account No. ___12-1095___
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Dated: ___March 12, 2003___

_____
Marcus J. Millet
Attorney Reg. No.: 28,241

LERNER, DAVID, LITTENBERG, KRUMHOLZ & MENTLIK, LLP
600 South Avenue West
Westfield, New Jersey 07090
(908) 654-5000

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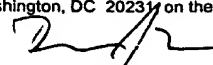
Dated: March 12, 2003   Signature: _____ (Marcus J. Millet)

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Docket No.: TESSERA 3.0-109 CIP DIV
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: :
Kim et al   :
                                       :
Application No.: 09/776,356   : Group Art Unit: 2827
                                       :
Filed: February 2, 2001   : Examiner: D. Graybill
                                       :
For: STACKED MICROELECTRONIC ASSEMBLY :
     AND METHOD THEREFOR   :

Commissioner for Patents
Washington, DC 20231

AMENDMENT

Dear Sir:

In response to the Official Action mailed September 12, 2002, applicant submits the following amendments and remarks.

IN THE CLAIMS

1. (AMENDED) A method of making a stacked microelectronic assembly comprising the steps of:

I. providing a flexible substrate having a plurality of attachment sites, said flexible substrate including a first surface and a second surface and having a plurality of electrically conductive terminals accessible at at least one of said first and second surfaces; test contacts accessible at at least one of said first and second surfaces; and wiring connected to said terminals and test contacts, said wiring including flexible leads extending to said attachment sites;

II. assembling a plurality of microelectronic elements to said attachment sites;